

## Essemtec Wins 2025 Mexico Technology Award for Multi-Function Component Placement with Puma Ultra All-in-One

**Aesch, Switzerland — September 2025** — Essemtec, a global leader in adaptive, highly flexible surface mount technology (SMT) solutions, is proud to announce that its Puma Ultra All-in-One Platform has been awarded a 2025 Mexico Technology Award in the category of Component Placement Equipment – Multi-function. The award was presented during a ceremony at SMTA Guadalajara, recognizing technology that drives innovation and performance in Mexico's electronics manufacturing industry and around the world.



Designed to meet the growing demands of high-mix, low- to mid-volume production, the Puma Ultra All-in-One integrates multiple functions—including Pick & Place, jetting, dispensing, and inspection (2D SPI & 2D AOI) —into one compact and modular platform. This flexible architecture allows manufacturers to scale capabilities over time without the cost or complexity of multiple standalone machines.

“The Puma Ultra was engineered in close collaboration with OEMs and EMS providers who needed a truly multifunctional solution that doesn’t compromise on speed, versatility or precision,” said Pierre-Jean Cancalon, Head of Marketing & Communications at Essemtec. “This award reflects the growing need for integrated systems that adapt to evolving production requirements.”

### Key Advantages of Puma Ultra:

- **Higher Throughput:** With a placement speed of up to 30,000 cph, Puma Ultra significantly outpaces earlier models—reducing cycle times by over 25% in customer environments.
- **High Speed Solder Paste Jetting:** With a shockwave valve technology, the Puma ultra All-in-One is able to jet solder paste at a frequency of 720,000dots/hour which translates to almost 500,000 dots/hour on a BGA Pattern and average speed of 310,000dots/hour for traditional board. It could perfectly complement a traditional screen printer to avoid stepped stencil or small dots and fine pitch or replace completely the printer.



- **Modular Upgradability:** The system supports 2D SPI & 2D AOI inspection, integrated solder paste Jetting, and integrated epoxy dispensing without machine replacement—offering a future-proof investment.
- **Precision and Versatility:** Supports components from 008004 chips to large custom parts up to **109x87 mm** with outstanding accuracy and repeatability.
- **Smart Software:** Includes inspection with auto-correction, integrated fiducial alignment, and in-line process feedback—ideal for PoP, SiP, and other advanced package applications. All process are manage with the same software enabling an extremely fast learning curve.

With hot swap feeder changeovers, off-line job prep, and high feeder capacity, Puma Ultra streamlines changeovers and maximizes uptime in fast-paced production environments.

The Mexico Technology Awards, organized by Mexico EMS, recognize excellence in electronics manufacturing equipment, materials, and software that help advance the production capabilities of the region's electronics sector. For more information, visit: [www.mexicoems.com/mta-awards](http://www.mexicoems.com/mta-awards)

For more information about Essemtec and its full line of adaptive SMT solutions, visit [www.essemtec.com](http://www.essemtec.com).

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### About Essemtec

Essemtec is renowned for its adaptive, highly flexible SMT pick-and-place equipment, sophisticated dispensers suitable for both high-speed and micro-dispensing, and intelligent production material storage and logistic systems. All products are equipped with advanced software packages, ensuring efficient material management and user-friendly operation. Essemtec's solutions are implemented worldwide across various industries, reflecting the company's commitment to quality and innovation.